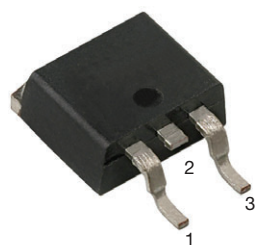
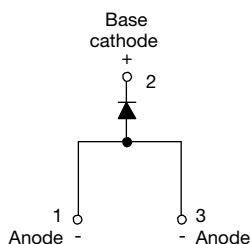


Surface Mount Fast Soft Recovery Rectifier Diode, 10 A


D²PAK (TO-263AB)


FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Glass passivated pellet chip junction
- AEC-Q101 qualified
- Meets JESD 201 class 1A whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V_F rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	10 A
V_R	600 V
V_F at I_F	1.2 V
I_{FSM}	140 A
t_{rr}	50 ns
T_J max.	150 °C
Snap factor	0.6
Package	D ² PAK (TO-263AB)
Circuit configuration	Single

APPLICATIONS

- Input rectification
- On-board and off-board EV / HEV battery chargers

DESCRIPTION

The VS-10ETF06SLHM3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
V_{RRM}		600	V
$I_{F(AV)}$	Sinusoidal waveform	10	A
I_{FSM}		140	
t_{rr}	1 A, 100 A/μs	50	ns
V_F	10 A, $T_J = 25$ °C	1.2	V
T_J	Range	-40 to +150	°C

VOLTAGE RATINGS

PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
VS-10ETF06SLHM3	600	700	2.5

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 128$ °C, 180° conduction half sine wave	10	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	115	
		10 ms sine pulse, no voltage reapplied	140	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	66	A ² s
		10 ms sine pulse, no voltage reapplied	94	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	940	A ² √s

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	10 A, $T_J = 25\text{ }^{\circ}\text{C}$		1.2	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$		12.7	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$			1.25	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$		2.5	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Reverse recovery time	t_{rr}	I_F at 10 A _{pk} 25 A/ μs 25 $^{\circ}\text{C}$	200	ns	
Reverse recovery current	I_{rr}		2.75	A	
Reverse recovery charge	Q_{rr}		0.32	μC	
Snap factor	S		0.6		

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	$^{\circ}\text{C}$
Maximum thermal resistance junction to case	R_{thJC}	DC operation	1.5	$^{\circ}\text{C/W}$
Maximum thermal resistance junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		40	
Approximate weight			2	g
			0.07	oz.
Marking device		Case style D ² PAK (TO-263AB)	10ETF06SH	

Note

(1) When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 $^{\circ}\text{C/W}$.

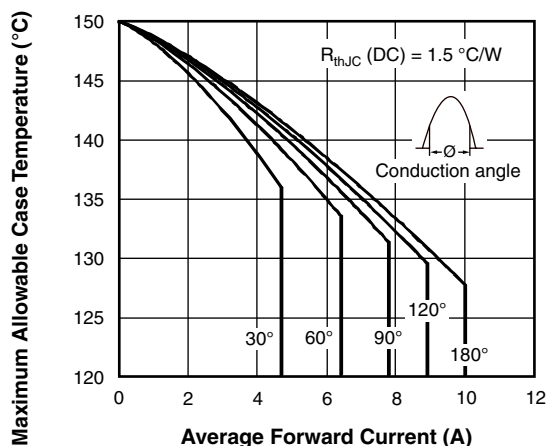


Fig. 1 - Current Rating Characteristics

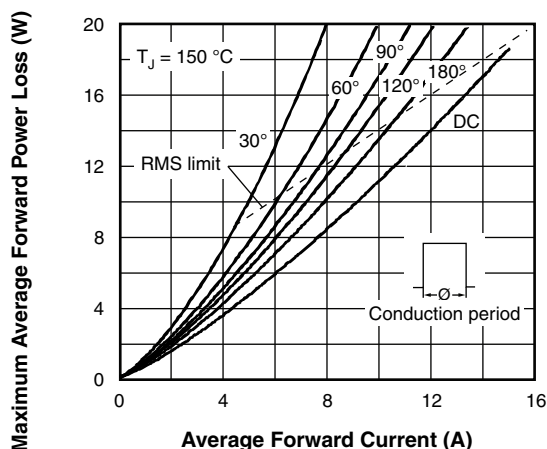


Fig. 4 - Forward Power Loss Characteristics

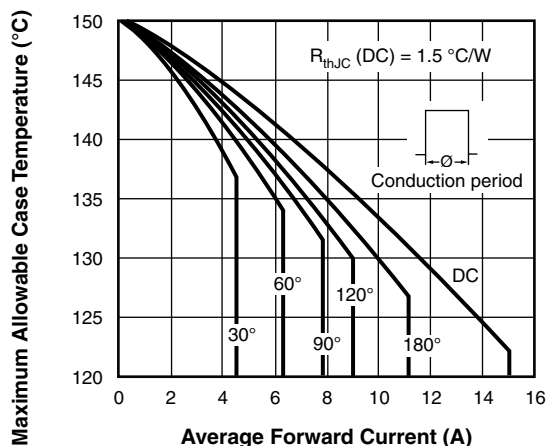


Fig. 2 - Current Rating Characteristics

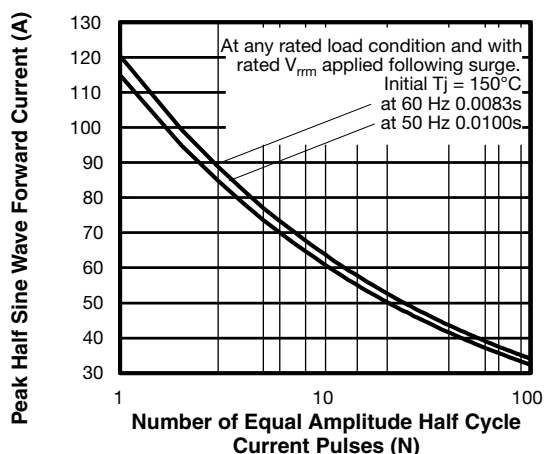


Fig. 5 - Maximum Non-Repetitive Surge Current

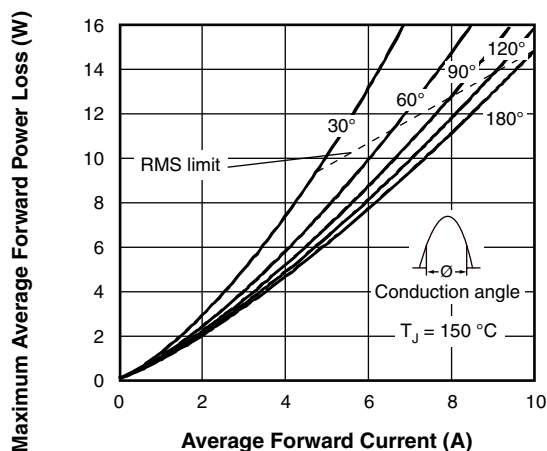


Fig. 3 - Forward Power Loss Characteristics

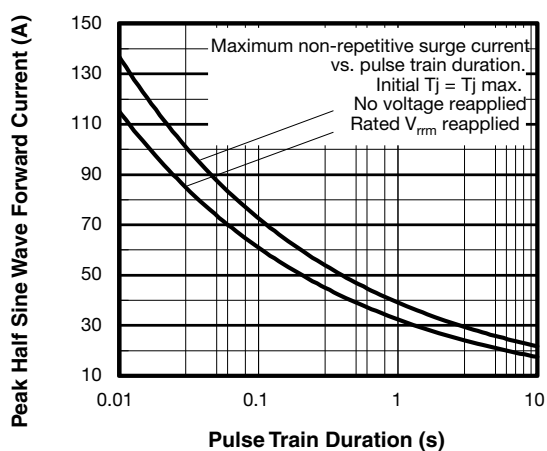


Fig. 6 - Maximum Non-Repetitive Surge Current

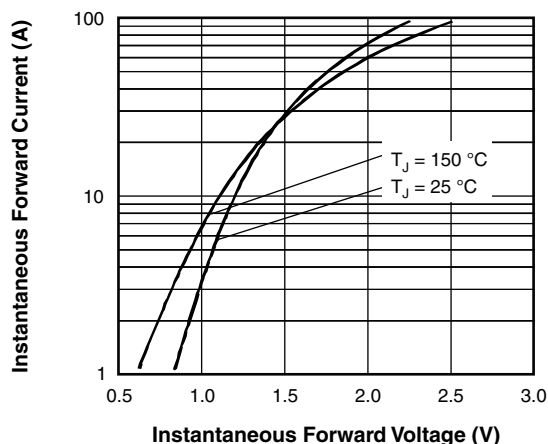
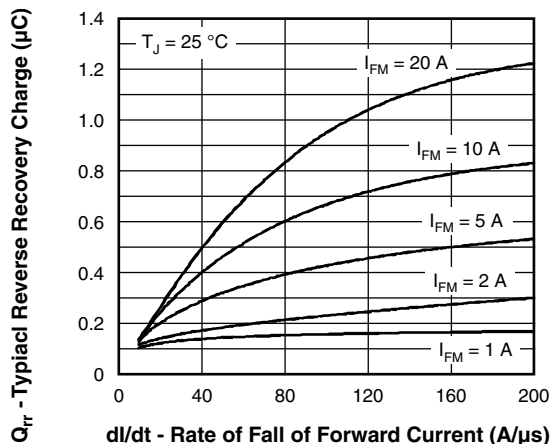
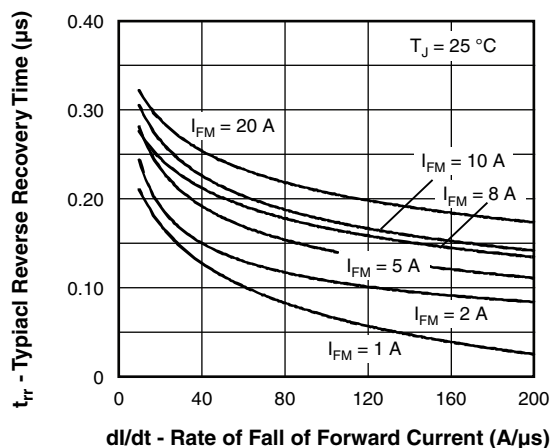
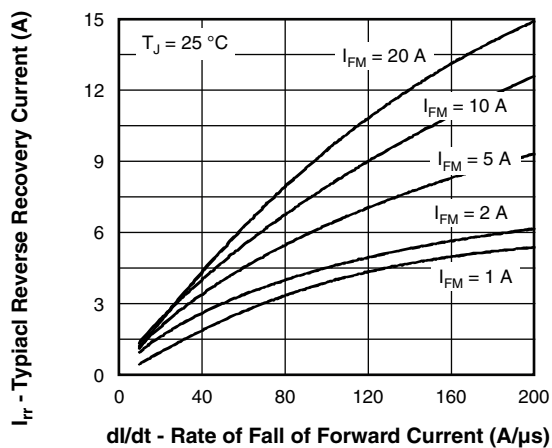
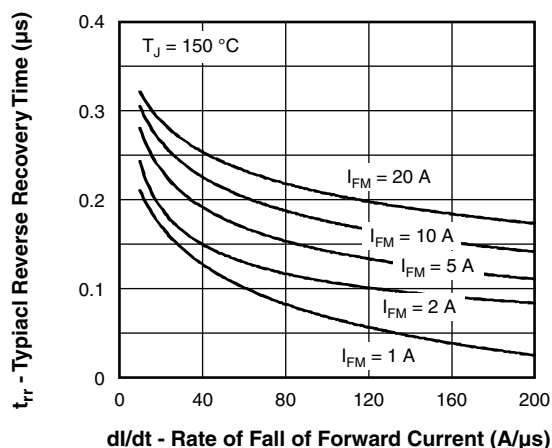
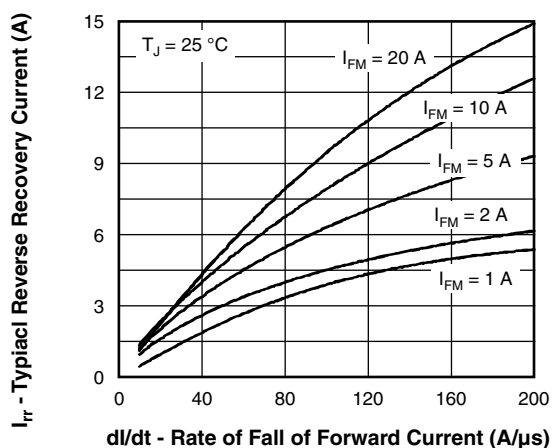


Fig. 7 - Forward Voltage Drop Characteristics


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

Fig. 12 - Recovery Current Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

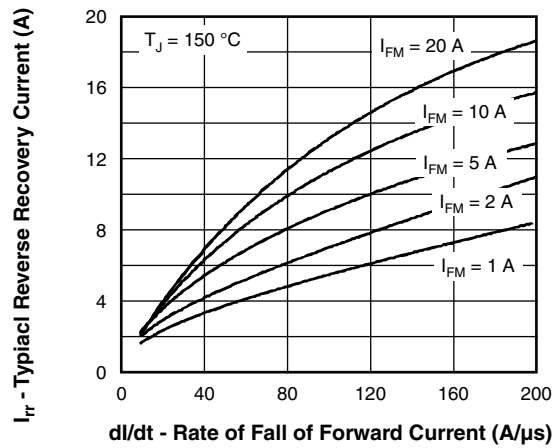


Fig. 13 - Recovery Current Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

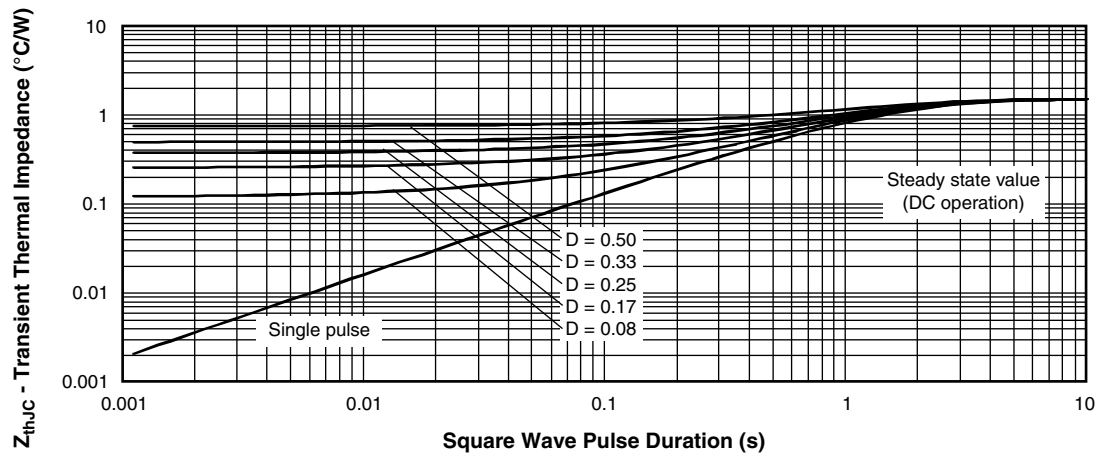


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

**ORDERING INFORMATION TABLE**

Device code	VS-	10	E	T	F	06	S	L	H	M3
	1	2	3	4	5	6	7	8	9	10

- 1** - Vishay Semiconductors product
- 2** - Current rating (10 = 10 A)
- 3** - Circuit configuration:
E = single
- 4** - Package:
T = D²PAK (TO-263AB)
- 5** - Type of silicon:
F = fast soft recovery rectifier
- 6** - Voltage code x 100 = V_{RRM} — **06 = 600 V**
- 7** - S = surface mountable
- 8** - L = tape and reel (left oriented), for different orientation, contact factory
- 9** - H = AEC-Q101 qualified
- 10** - Environmental digit:
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10ETF06SLHM3	800	800	13" diameter reel

LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95444
Packaging information	www.vishay.com/doc?96317



D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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